

# PMEG4002EB

0.2 A very low  $V_F$  MEGA Schottky barrier rectifier in SOD523 package

Rev. 02 — 13 January 2010

Product data sheet

## 1. Product profile

### 1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD523 (SC-79) ultra small and flat lead Surface Mounted Device (SMD) plastic package.

### 1.2 Features

- Forward current: 200 mA
- Reverse voltage: 40 V
- Very low forward voltage
- Ultra small and flat lead SMD plastic package

### 1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Inverse polarity protection
- Low power consumption applications

### 1.4 Quick reference data

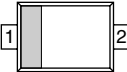

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_F$	forward current		-	-	200	mA
$V_R$	reverse voltage		-	-	40	V
$V_F$	forward voltage	$I_F = 200$ mA	[1] -	520	600	mV

[1] Pulse test:  $t_p \leq 300$   $\mu$ s;  $\delta \leq 0.02$ .

## 2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Symbol
1	cathode	[1]	1  2
2	anode		<i>sym001</i>

[1] The marking bar indicates the cathode.

## 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG4002EB	SC-79	plastic surface mounted package; 2 leads	SOD523

## 4. Marking

Table 4. Marking codes

Type number	Marking code
PMEG4002EB	L9

## 5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_R$	reverse voltage		-	40	V
$I_F$	forward current		-	200	mA
$I_{FRM}$	repetitive peak forward current	$t_p \leq 1$ s; $\delta \leq 0.5$	-	300	mA
$I_{FSM}$	non-repetitive peak forward current	$t_p = 8.3$ ms half sine wave; JEDEC method	-	1	A
$T_j$	junction temperature		-	150	°C
$T_{amb}$	ambient temperature		-65	+150	°C
$T_{stg}$	storage temperature		-65	+150	°C

## 6. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2] -	-	450	K/W

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] For Schottky barrier diodes thermal run-away has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses. Nomograms for determining the reverse power losses  $P_R$  and  $I_{F(AV)}$  rating will be available on request.

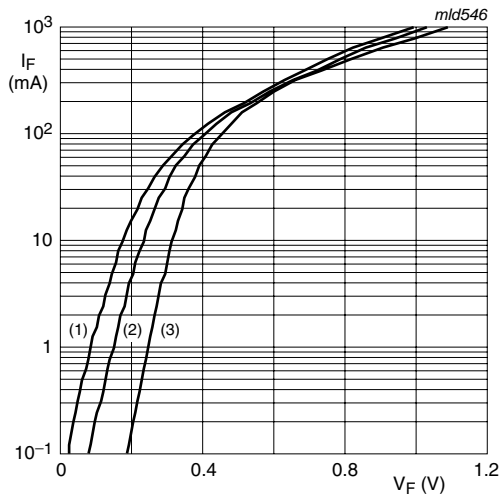
## 7. Characteristics

**Table 7. Characteristics**

$T_{amb} = 25\text{ }^\circ\text{C}$  unless otherwise specified.

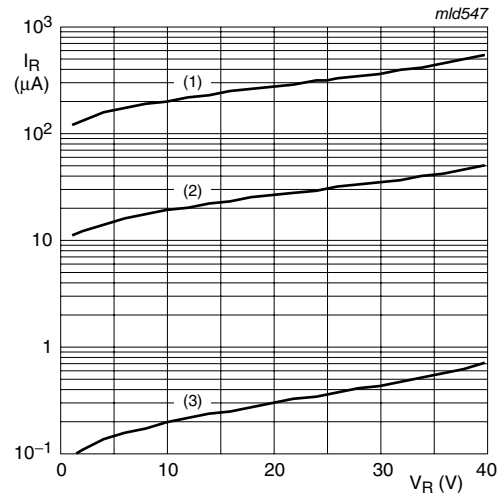
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_F$	forward voltage	$I_F = 0.1\text{ mA}$	-	190	220	mV
		$I_F = 1\text{ mA}$	-	250	290	mV
		$I_F = 10\text{ mA}$	-	320	360	mV
		$I_F = 100\text{ mA}$	-	440	500	mV
		$I_F = 200\text{ mA}$	-	520	600	mV
$I_R$	reverse current	$V_R = 25\text{ V}$	[1] -	-	0.5	$\mu\text{A}$
$C_d$	diode capacitance	$V_R = 1\text{ V}; f = 1\text{ MHz}$	-	-	20	pF

[1] Pulse test:  $t_p \leq 300\text{ }\mu\text{s}$ ;  $\delta \leq 0.02$ .



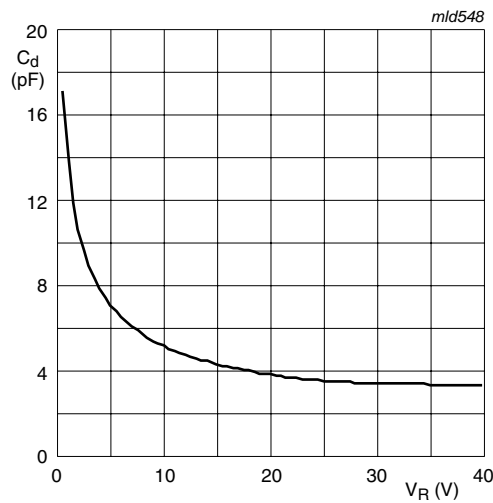
- (1)  $T_{amb} = 125^\circ\text{C}$
- (2)  $T_{amb} = 85^\circ\text{C}$
- (3)  $T_{amb} = 25^\circ\text{C}$

**Fig 1. Forward current as a function of forward voltage; typical values**



- (1)  $T_{amb} = 125^\circ\text{C}$
- (2)  $T_{amb} = 85^\circ\text{C}$
- (3)  $T_{amb} = 25^\circ\text{C}$

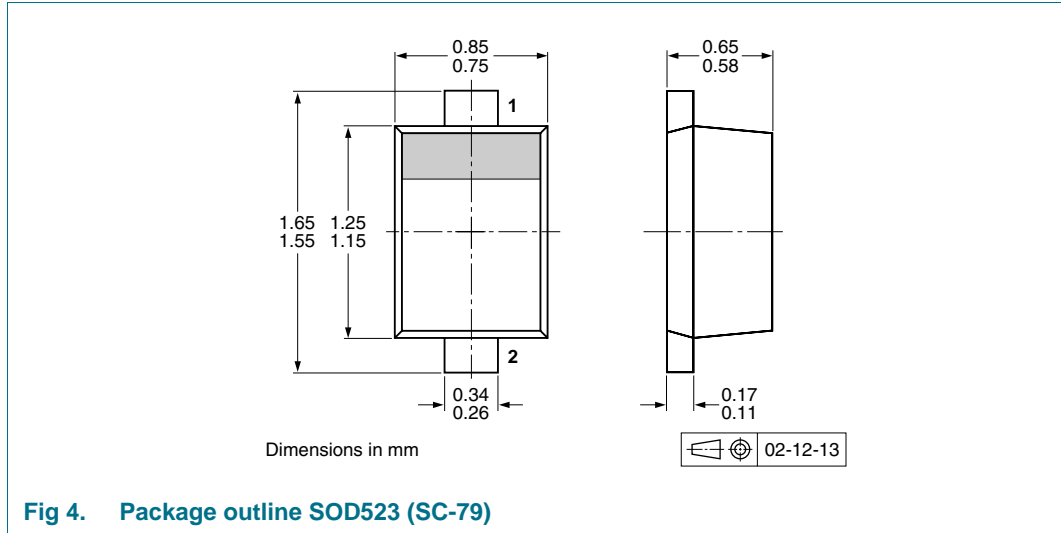
**Fig 2. Reverse current as a function of reverse voltage; typical values**



$T_{amb} = 25^\circ\text{C}$ ;  $f = 1\text{ MHz}$

**Fig 3. Diode capacitance as a function of reverse voltage; typical values**

**8. Package outline**



**Fig 4. Package outline SOD523 (SC-79)**

**9. Packing information**

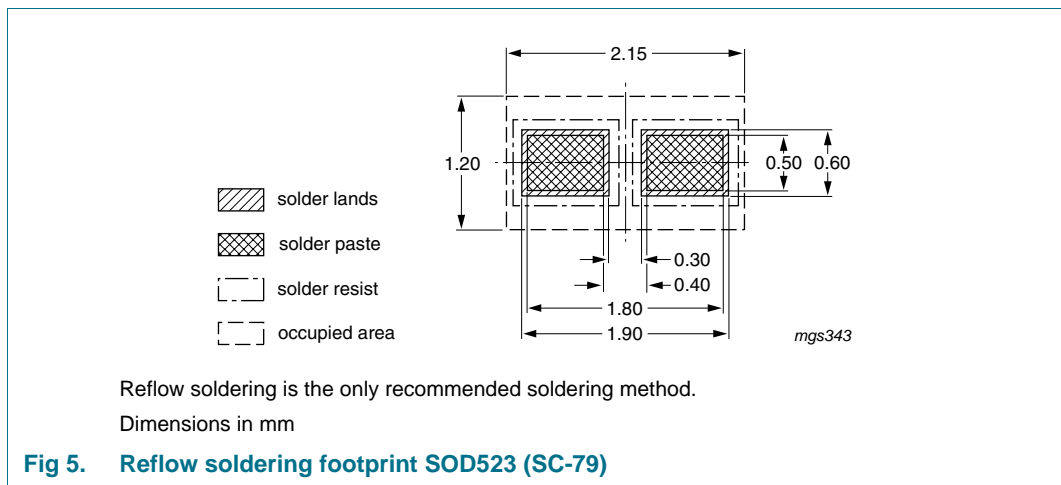
**Table 8. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

Type number	Package	Description	Packing quantity	
			3000	10000
PMEG4002EB	SOD523	4 mm pitch, 8 mm tape and reel	-115	-135

[1] For further information and the availability of packing methods, see [Section 13](#).

**10. Soldering**



## 11. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMEG4002EB_2	20100113	Product data sheet	-	PMEG4002EB_1
Modifications:		<ul style="list-style-type: none"><li>This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content.</li><li><a href="#">Figure 5 "Reflow soldering footprint SOD523 (SC-79)": updated</a></li></ul>		
PMEG4002EB_1	20050712	Product data sheet	-	-

## 12. Legal information

### 12.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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